

Semiconductor Devices Spring 2019

ROYAL INSTITUTE OF TECHNOLOGY

Lecture 8



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This Lecture

- Reading
 - Chapter 5, sections 1-6
- Concepts:
 - Metal-oxide-semiconductor (MOS)
 - The FIELD effect transistor (focus on p-channel)

Figure 5.2 An MOS transistor is an MOS capacitor with PN junctions at two ends.



Figure 6.1 (a) Basic MOSFET structure and (b) IV characteristics.





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Figure 6.2 Two ways of representing a MOSFET: (a) a circuit symbol and (b) as an on/offswitch.





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Figure 5.1 The MOS capacitor.



Figure 5.3 (a) Polysilicon-gate/oxide/semiconductor capacitor and (b) its energy band diagram with no applied voltage.



Figure 5.4 Energy band diagram of the MOS system at the flat-band condition. A voltage equal to V_{fb} is applied between the N⁺-poly-Si gate and the P-silicon body to achieve this condition. ψ_g is the gate-material work function, and ψ_s is the semiconductor work function. E_0 is the vacuum level.



Figure 5.5 This MOS capacitor is biased into surface accumulation ($p_s > p_0 = N_a$). (a) Types of charge present. \oplus represents holes and – represents negative charge. (b) Energy band diagram.





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Figure 5.6 This MOS capacitor is biased into surface depletion. (a) Types of charge present; (b) energy band diagram.



Figure 5.7 The threshold condition is reached when $n_s = N_a$, or equivalently, A = B, or $\phi_s = \phi_{st} = 2 \phi_B$. Note that positive ϕ_{st} corresponds to downward band bending.



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Figure 5.8 Theoretical threshold voltage vs. body doping concentration using Eq. (5.4.3). See Section 5.5.1 for a discussion of the gate doping type.



Figure 5.9 An MOS capacitor biased into inversion. (a) Types of charge present; (b) energy band diagram with arrow indicating the sense of positive V_{g} .



Figure 5.10 (a) The surface inversion behavior is best studied with a PN junction butting the MOS capacitor to supply the inversion charge. (b) The inversion layer may be thought of as a thin N-type layer.



Figure 5.11 Surface potential saturates at $2\phi_B$ when V_g is larger than V_t .





Figure 5.12 Depletion-region width in the body of an MOS capacitor.





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Figure 5.13 Components of charge (C/cm²) in the MOS capacitor substrate: (a) depletion-layer charge; (b) inversion-layer charge; and (c) accumulation-layer charge.





Figure 5.14 The total substrate charge, Q_{sub} (C/cm²), is the sum of Q_{acc} , Q_{dep} , and Q_{inv} .



Figure 5.24 Average location of the inversion-layer electrons is about 15 Å below the Si–SiO₂ interface. Poly-Si gate depletion is also shown.



Figure 5.15 Setup for the C–V measurement.





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Figure 5.16 The quasi-static MOS C–V characteristics.



Figure 5.17 Illustration of the MOS capacitor in all bias regions with the depletion-layers shaded. (a) Accumulation region; (b) depletion region; (c) inversion region with efficient supply of inversion electrons from the N region corresponding to the transistor C-V or the quasi-static C-V; and (d) inversion region with no supply of inversion electrons (or weak supply by thermal generation) corresponding to the high-frequency capacitor C-V case.



